

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Rupasree DAS</td> <td>04/14/2008</td> </tr> <tr> <td>Chang Ho NOH</td> <td>04/14/2008</td> </tr> <tr> <td>So Yeon PARK</td> <td>04/14/2008</td> </tr> </tbody> </table>		Name	Execution Date	Rupasree DAS	04/14/2008	Chang Ho NOH	04/14/2008	So Yeon PARK	04/14/2008
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Rupasree DAS	04/14/2008								
Chang Ho NOH	04/14/2008								
So Yeon PARK	04/14/2008								
RECEIVING PARTY DATA									
Name:	SAMSUNG ELECTRONICS CO., LTD.								
Street Address:	416, Maetan-dong, Yeongtong-gu								
City:	Suwon-si, Gyeonggi-do								
State/Country:	REPUBLIC OF KOREA								
Postal Code:	442-742								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12114950</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12114950				
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Application Number:	12114950								
CORRESPONDENCE DATA									
Fax Number:	(860)286-0115								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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Address Line 2:	22nd Floor								
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ATTORNEY DOCKET NUMBER:	PHO-0118								
NAME OF SUBMITTER:	Ian J.S. Lodovice								

Total Attachments: 3
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ASSIGNMENT

WHEREAS We, **Rupasree Ragini DAS** of **107-804, Hwanggol Maeul Jugong 1 Danji Apartment, Yeongtong-dong, Paldal-gu, Suwon-si, Gyeonggi-do, 443-740 Republic of Korea**, **Change Ho NOH** of **702-1904, Salgugol 7 Danji Apartment, Yeongtong-dong, Paldal-gu, Suwon-si, Gyeonggi-do, 443-736 Republic of Korea** and **So Yeon PARK** of **Samsung Advanced Institute of Technology, Nongseo-dong, Giheung-gu, Yongin-si, Gyeonggi-do, 446-712 Republic of Korea** (hereinafter referred to as "ASSIGNORS"); have invented certain new and useful improvements in:

ELECTROCHROMIC MATERIALS AND ELECTROCHROMIC DEVICES USING THE SAME

which claims priority to **Korean** Application No. 10-2007-118369, filed on 20 November 2007, and for which We are about to file an application for Letters Patent of the United States;

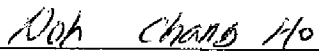
AND WHEREAS, **SAMSUNG ELECTRONICS CO., LTD.** (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of **Korea**, having a place of business at **416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, 442-742 Republic of Korea**, is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that

the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: _____  _____ L.S.
Rupasree Ragini DAS

Date: _____  _____ L.S.
Chang Ho NOH

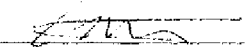
Date: _____ _____ L.S.
So Yeon PARK

the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: _____ L.S.
Rupasree DAS

Date: _____ L.S.
Chang Ho NOH

Date: 04.14.2008 L.S.

So Yeon PARK